

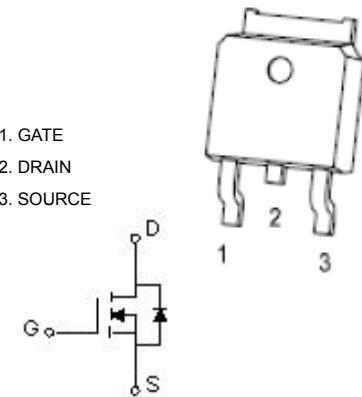
TO-252-2L Plastic-Encapsulate MOSFETS

CJU02N60 N-Channel Power MOSFET

General Description

The high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition , this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes . The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power suppliers, converters and PWM motor controls , these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

TO-252-2L



FEATURES

- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- $I_{DS(on)}$ and $V_{DS(on)}$ Specified at Elevated Temperature

Maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	2	A
Pulsed Drain Current	I_{DM}	8	
Power Dissipation	P_D	1.25	W
Single Pulsed Avalanche Energy*	E_{AS}	128	mJ
Thermal Resistance from Junction to Ambient	R_{JA}	100	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-50 ~ +150	

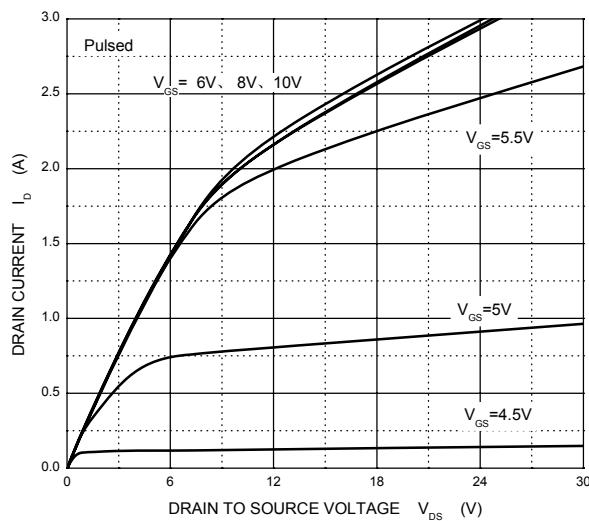
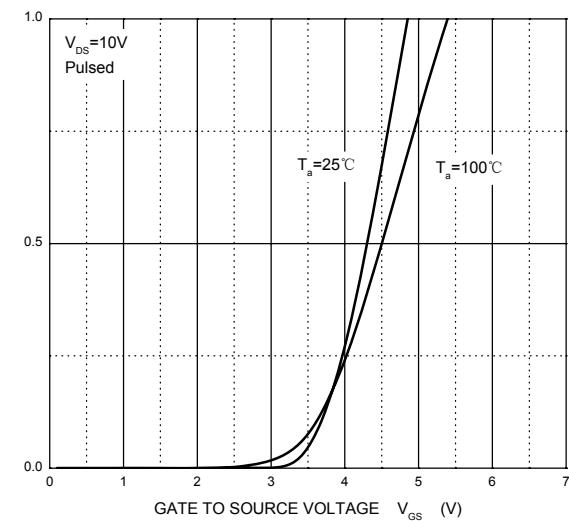
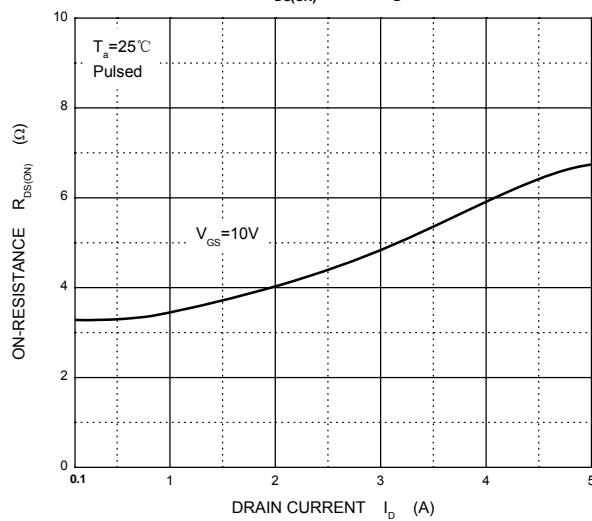
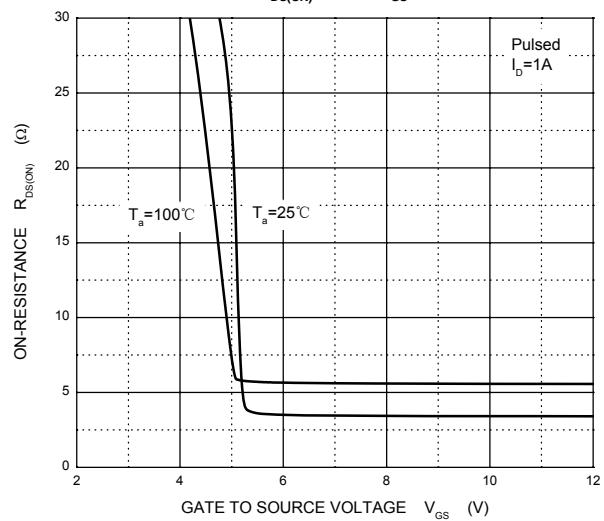
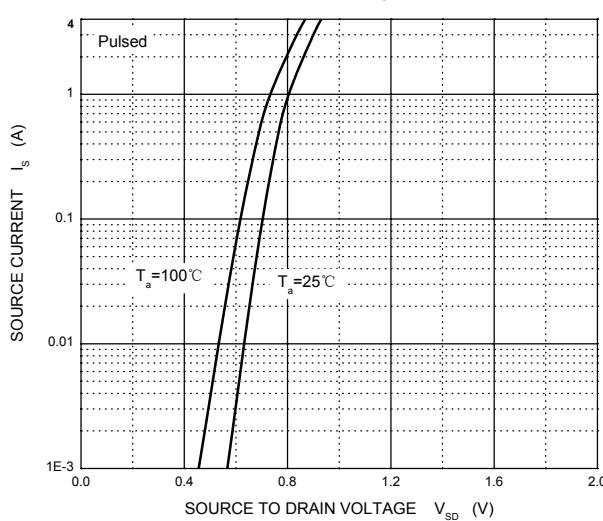
* E_{AS} condition: $T_J=25^\circ\text{C}$, $V_{DD}=50\text{V}$, $L=64\text{mH}$, $I_{AS}=2\text{A}$, $R_G=25\Omega$

Electrical characteristics ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS}=0V, I_D=250\mu\text{A}$	600			V
Gate-Threshold Voltage (note1)	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0		4.0	
Gate-Body Leakage Current (note1)	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm20V$			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			25	μA
Drain-Source On-State Resistance (note1)	$R_{DS(\text{on})}$	$V_{GS}=10V, I_D=1\text{A}$			4.4	Ω
Forward Transconductance (note1)	g_{fs}	$V_{DS}=50V, I_D=1\text{A}$	1			S
Input Capacitance (note2)	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$		435		pF
Output Capacitance (note2)	C_{oss}			56		
Reverse Transfer Capacitance (note2)	C_{rss}			9.2		
Turn-On Delay Time (note2)	$t_{d(on)}$	$V_{DD}=300V, I_D=2\text{A}, V_{GS}=10V, R_G=18\Omega$		12		ns
Rise Time (note2)	t_r			21		
Turn-Off Delay Time (note2)	$t_{d(off)}$			30		
Fall Time (note2)	t_f			24		
Forward on Voltage(note1)	V_{SD}	$V_{GS}=0V, I_S=2\text{A}$			1.6	V

Notes:

1. Pulse Test : Pulse Width $\leq300\mu\text{s}$, duty cycle $\leq2\%$.
2. These parameters have no way to verify.

Output Characteristics**Transfer Characteristics** $R_{DS(ON)}$ — I_D  $R_{DS(ON)}$ — V_{GS}  I_S — V_{SD} **Threshold Voltage**